

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7165843

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HSIEN-WEN WAN	08/06/2020
YI-TING CHENG	08/06/2020
MING-HWEI HONG	08/06/2020
JUEI-NAI KWO	08/06/2020
BO-YU YANG	08/06/2020
YU-JIE HONG	08/06/2020

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	8, LI-HSIN RD. 6
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City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
Name:	NATIONAL TAIWAN UNIVERSITY
Street Address:	NO.1, SEC. 4, ROOSEVELT ROAD
City:	TAIPEI
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Postal Code:	10617

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17666347

CORRESPONDENCE DATA

Fax Number:

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ATTORNEY DOCKET NUMBER:	T1516.10730US02
NAME OF SUBMITTER:	R. BURNS ISRAELSEN
SIGNATURE:	/R. Burns Israelsen, Reg. No. 42685/
DATE SIGNED:	02/08/2022
Total Attachments: 2 source=T1516-10730US02_Assignment#page1.tif source=T1516-10730US02_Assignment#page2.tif	

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

The PATENT RIGHTS referred to in this agreement are:

- (check one) a patent application for this invention, executed by the ASSIGNOR(S) concurrently with this assignment.
- U.S. patent application Serial No. 16/945,199, filed July 31, 2020
- a U.S. patent application based on PCT International Application No. _____ filed on (date) _____ (U.S. patent application Serial No. _____, if known).
- U.S. patent No. _____, issued _____.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

- U.S. patent rights only.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) 1. TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
2. NATIONAL TAIWAN UNIVERSITY

(Address) 1. NO. 8, LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN 300, R.O.C.
2. NO. 1, SEC. 4, ROOSEVELT ROAD, TAIPEI 10617, TAIWAN, R.O.C.

The ASSIGNEE is:

- (check one) An individual.
- A Partnership.
1. A Corporation of TAIWAN, R.O.C.
2. A University of TAIWAN, R.O.C.
- (other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, hereby assign(s) the following rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO
ASSIGNEE: 1.TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
2.NATIONAL TAIWAN UNIVERSITY

INVENTION TITLE: SEMICONDUCTOR DEVICE AND MANUFACTURING
METHOD THEREOF

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

<u>Hsien-Wen WAN</u> Name of sole or first inventor	<u>Hsien Wen Wan</u> Signature	<u>2020.08.06</u> Date
<u>Yi-Ting CHENG</u> Name of second inventor, if any	<u>Yi-Ting Cheng</u> Signature	<u>2020.08.06</u> Date
<u>Ming-Hwei HONG</u> Name of third inventor, if any	<u>Minghwa Hong</u> Signature	<u>2020.08.06</u> Date
<u>Juei-Nai KWO</u> Name of fourth inventor, if any	<u>Juei Nai Kwo</u> Signature	<u>2020.08.06</u> Date
<u>Bo-Yu YANG</u> Name of fifth inventor, if any	<u>Bo-Yu Yang</u> Signature	<u>2020.08.06</u> Date
<u>Yu-Jie HONG</u> Name of sixth inventor, if any	<u>Yu-Jie Hong</u> Signature	<u>2020.08.06</u> Date

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RECORDED: 02/08/2022

REEL: 058932 FRAME: 0156